



#### 30V +175°C N-CHANNEL ENHANCEMENT MODE MOSFET PowerDI5060-8

## **Product Summary**

BV <sub>DSS</sub>	Rds(on)	I <sub>D</sub> T <sub>C</sub> = +25°C
30V	$0.55 \text{m}\Omega$ @ V <sub>GS</sub> = 10V	150A
307	$0.95 \text{m}\Omega$ @ $V_{GS} = 4.5 \text{V}$	120A

## **Description and Applications**

This new generation MOSFET is designed to minimize R<sub>DS(ON)</sub> yet maintain superior switching performance. This device is ideal for use in notebook battery power managements and load switches.

- Body control electronics
- DC-DC converters

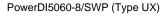
#### **Features**

- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switch (UIS) Test in Production
- Thermally Efficient Package Cooler Running Applications
- High Conversion Efficiency
- Low R<sub>DS(ON)</sub> Minimizes On State Losses < 1.1mm Package Profile – Ideal for Thin Applications
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- The DMTH3M70LPSWQ is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.

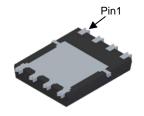
https://www.diodes.com/quality/product-definitions/

#### **Mechanical Data**

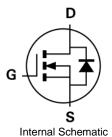
- Package: PowerDI<sup>®</sup>5060-8
- Package Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: See Diagram Below
- Terminals: Finish Matte Tin Annealed over Copper Leadframe.
   Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.097 grams (Approximate)

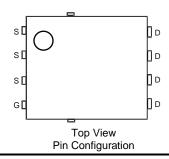






Top View Bottom View





### Ordering Information (Note 4)

Part Number	Backago	Packing		
Fait Number	Package	Qty.	Carrier	
DMTH3M70LPSWQ-13	PowerDI5060-8/SWP (Type UX)	2,500	Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant. All applicable RoHS exemptions applied.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

## **Marking Information**



Oll = Manufacturer's Marking
TH3M70LSW = Product Type Marking Code
YYWW = Date Code Marking
YY = Last Two Digits of Year (ex: 24 = 2024)
WW = Week Code (01 to 53)



## **Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit	
Drain-Source Voltage	VDSS	30	V	
Gate-Source Voltage	$V_{GSS}$	±20	V	
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 7)	$T_C = +25$ °C $T_C = +70$ °C	l <sub>D</sub>	150 125	А
Continuous Drain Current, V <sub>GS</sub> = 10V (Note 6)	lD	61 49	А	
Pulsed Drain Current (380µs Pulse, Duty Cycle = 1%)	I <sub>DM</sub>	600	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	4.48	Α	
Pulsed Body Diode Forward Current (380µs Pulse, Duty Cycle = 19	Ism	600	Α	
Avalanche Current, L = 0.3mH (Note 8)	las	48	Α	
Avalanche Energy, L = 0.3mH (Note 8)	Eas	345	mJ	

## **Thermal Characteristics**

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)		PD	2.13	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{ heta JA}$	58.6	°C/W
Total Power Dissipation (Note 6)		PD	3.85	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	$R_{\theta JA}$	32.5	°C/W
Thermal Resistance, Junction to Case (Note 7)		R <sub>θ</sub> JC	1.04	°C/W
Operating and Storage Temperature Range		$T_{J_i}T_{STG}$	-55 to +175	°C

# **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

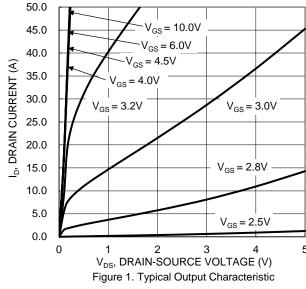
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 9)							
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_{D} = 1mA$	
Zero Gate Voltage Drain Current	IDSS	_	-	1	μΑ	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V	
Gate-Source Leakage	IGSS			±100	nA	$V_{GS} = \pm 20V$ , $V_{DS} = 0V$	
ON CHARACTERISTICS (Note 9)							
Gate Threshold Voltage	V <sub>GS(TH)</sub>	1		3	V	$V_{DS} = V_{GS}$ , $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D		0.39	0.55	mΩ	$V_{GS} = 10V, I_D = 20A$	
Static Diain-Source On-Nesistance	RDS(ON)	_	0.67	0.95		$V_{GS} = 4.5V, I_{D} = 20A$	
Diode Forward Voltage	$V_{SD}$	_	0.7	1	V	$V_{GS} = 0V, I_{S} = 20A$	
DYNAMIC CHARACTERISTICS (Note 10)							
Input Capacitance	C <sub>iss</sub>	_	11112		pF	\\ 45\\\\\ 0\\	
Output Capacitance	Coss		8689	1	pF	V <sub>DS</sub> = 15V, V <sub>GS</sub> = 0V f = 1MHz	
Reverse Transfer Capacitance	Crss	_	325		pF	1 - 1101112	
Gate Resistance	$R_g$		0.6	1	Ω	$V_{DS} = 0V$ , $V_{GS} = 0V$ , $f = 1MHz$	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg		152.7		nC		
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg		69.4	_	nC	V <sub>DS</sub> = 15V, I <sub>D</sub> = 20A	
Gate-Source Charge	Qgs	_	28.8	_	nC		
Gate-Drain Charge	$Q_{gd}$		10.3		nC		
Turn-On Delay Time	t <sub>D(ON)</sub>		15		ns		
Turn-On Rise Time	t <sub>R</sub>	_	29	_	ns	V <sub>DD</sub> = 15V, V <sub>GEN</sub> = 10V,	
Turn-Off Delay Time	tD(OFF)	_	89		ns	$R_{GEN} = 6\Omega$ , $I_D = 24A$	
Turn-Off Fall Time	t <sub>F</sub>	_	42		ns		

Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.
- 7. Thermal resistance from junction to soldering point (on the exposed drain pad).
- 8. I<sub>AS</sub> and E<sub>AS</sub> ratings are based on low frequency and duty cycles to keep T<sub>J</sub> = +25°C. 9. Short duration pulse test used to minimize self-heating effect.
- 10. Guaranteed by design. Not subject to product testing.







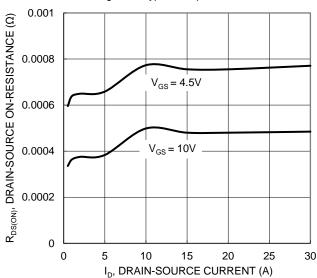


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

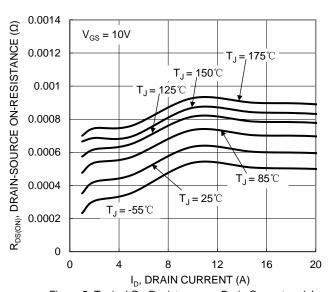


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature

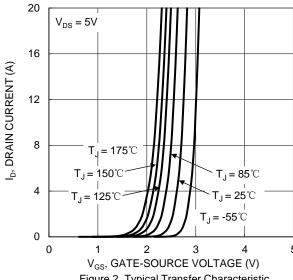


Figure 2. Typical Transfer Characteristic

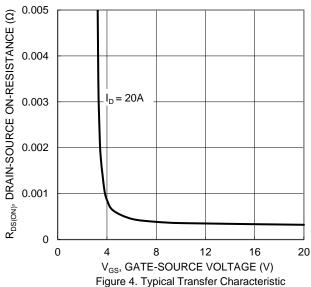


Figure 6. On-Resistance Variation with Junction Temperature





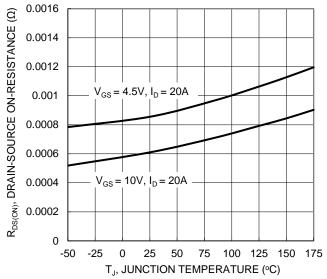


Figure 7. On-Resistance Variation with Junction Temperature

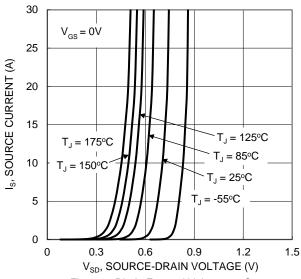
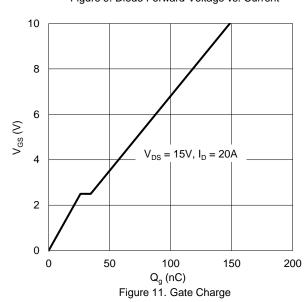
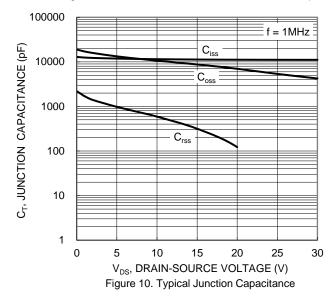


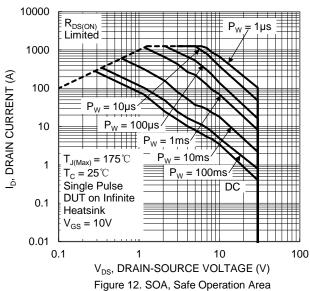
Figure 9. Diode Forward Voltage vs. Current



2.5 (S)  $\frac{1}{1000}$   $\frac{1}{100$ 

Figure 8. Gate Threshold Variation vs. Junction Temperature







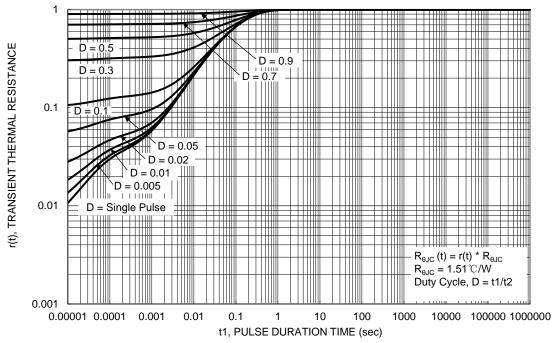


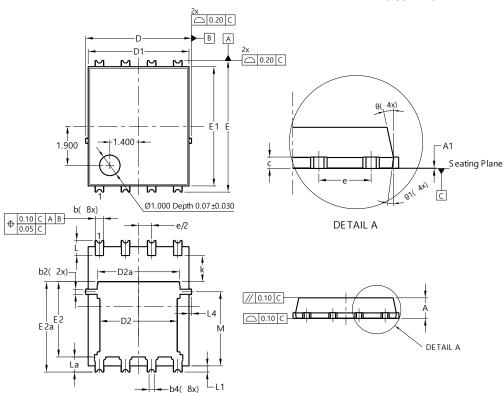
Figure 13. Transient Thermal Resistance



## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8/SWP (Type UX)

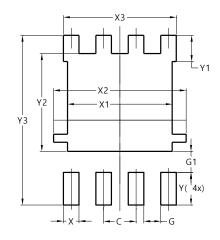


PowerDI5060-8/SWP				
(Type UX)				
Dim	Min	Max	Тур	
Α	0.90	1.10	1.00	
A1	0	0.05		
b	0.30	0.50	0.41	
b2	0.20	0.35	0.25	
b4	0	).25REF		
С	0.230	0.330	0.277	
D	5	.15 BS0	$\sim$	
D1	4.70	5.10	4.90	
D2	3.56	3.96	3.76	
D2a	3.78	4.18	3.98	
Е	6	.40 BS0		
E1	5.60	6.00	5.80	
E2	3.46	3.86	3.66	
E2a	4.195	4.595	4.395	
е	1.27BSC			
k	1.05			
L	0.635	0.835	0.735	
La	0.635	0.835	0.735	
L1	0.200	0.400	0.300	
L4	0.025	0.225	0.125	
M	3.205	4.005	3.605	
θ	10°	12°	11°	
θ1	6°	8°	7°	
All Dimensions in mm				

# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### PowerDI5060-8/SWP (Type UX)



Dimensions	Value (in mm)		
С	1.270		
G	0.660		
G1	0.820		
Х	0.610		
X1	4.100		
X2	5.190		
Х3	4.420		
Y	1.270		
Y1	1.020		
Y2	3.810		
Y3	6.610		



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